

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Koji SHIMIZU	05/12/2011
Hiroaki YATSUKAWA	05/12/2011
RECEIVING PARTY DATA	
Name:	MITSUI HIGH-TEC, INC.
Street Address:	10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi
City:	Fukuoka
State/Country:	JAPAN
Postal Code:	807-8588
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13129649
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NAME OF SUBMITTER:	Daniel B. Moon
Total Attachments: 3 source=P40167_assignment#page1.tif source=P40167_assignment#page2.tif source=P40167_assignment#page3.tif	

OP \$40.00 13129649

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PATENT
REEL: 026291 FRAME: 0151

ASSIGNMENT

WHEREAS, * Koji SHIMIZU*, a citizen of *Japan*, whose post office address is *c/o MITSUI HIGH-TEC, INC., 10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi, Fukuoka 807-8588 Japan*, and *Hiroaki YATSUKAWA*, a citizen of *Japan*, whose post office address is *c/o MITSUI HIGH-TEC, INC., 10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi, Fukuoka 807-8588 Japan*, hereinafter referred to as the ASSIGNORS, have invented a certain improvement relating to

Lead Frame, Semiconductor Apparatus Using this Lead Frame,
* Intermediate Product thereof and Manufacturing Method thereof

for which they have jointly executed, on the same date as this assignment, an application for Letters Patent of the United States to be filed in the United States Patent and Trademark Office.

If this Assignment is filed after the filing date of the above-identified application, the undersigned hereby authorize and request any one of the attorneys of record in this application including Neil F. Greenblum, Reg. No. 28,394, Bruce H. Bernstein, Reg. No. 29,027, Arnold Turk, Reg. No. 33,094, James L. Rowland, Reg. No. 32,674, Stephen M. Roylance, Reg. No. 31,296, Leslie J. Paperner, Reg. No. 33,329, William Pieprz, Reg. No. 33,630, Robert W. Mueller, Reg. No. 35,043, Andrew M. Calderon, Reg. No. 38,093 and William E. Lyddane, Reg. No. 41,568, of the firm Greenblum & Bernstein, P.L.C., whose address is 1950 Roland Clarke Place, Reston, Virginia 20191, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

AND WHEREAS, *MITSUI HIGH-TEC, INC.*, a corporation organized and existing under the laws of the State of *Japan*, whose post-office address is *10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi, Fukuoka 807-8588 Japan*, hereinafter known as the ASSIGNEE, is desirous of acquiring the entire right, title and interest for the United States in and to said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, and prolongations thereof.

NOW, THIS WITNESSETH that for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt whereof is hereby acknowledged, said ASSIGNORS hereby assign, sell and transfer to said ASSIGNEE, its assigns and legal representatives, the entire and exclusive right, title and interest in and to said invention and application, for the United States including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted therefor, said ASSIGNEE and its assigns and legal representatives to have, hold, exercise and enjoy the said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges, and

advantages in any ways arising from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when granted, including any and all renewals, reissues, and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives in as ample and beneficial a manner to all intents and purposes as the said ASSIGNORS might or could have held and enjoyed the same, if this assignment had not been made.

AND said ASSIGNORS hereby agree to execute all papers necessary to file applications in the United States for said invention and to assign the same to said ASSIGNEE, or any assignee acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing Letters Patent thereon.


AND said ASSIGNORS authorize and request the Commissioner of Patents to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

IN TESTIMONY WHEREOF, this assignment is executed by * Koji SHIMIZU *, this 12th day of May, 2011, at c/o MITSUI HIGH-TEC, INC., 10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi, Fukuoka 807-8588 Japan.

First Witness:

(Name)

(Date)



*Koji SHIMIZU *

Second Witness:

(Name)

(Date)

IN TESTIMONY WHEREOF, this assignment is executed by *Hiroaki YATSUKAWA*, this 12th day of May, 2011, at c/o MITSUI HIGH-TEC, INC., 10-1, Komine 2-chome, Yahatanishi-ku, Kitakyushu-shi, Fukuoka 807-8588 Japan.

First Witness:

(Name)

(Date)

Hiroaki Yatsukawa
*Hiroaki YATSUKAWA *

Second Witness:

(Name)

(Date)